

### Features

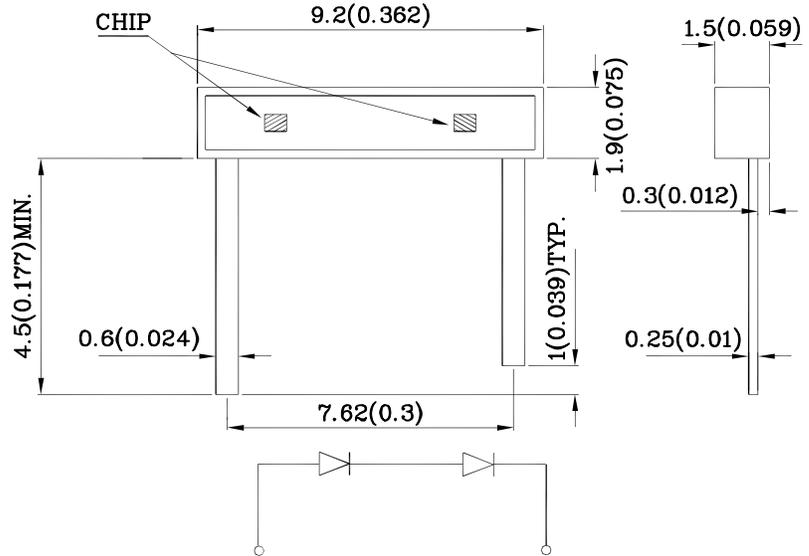
- Low power consumption
- Ideal for backlighting
- RoHS compliant

#### Application Note:

As silicone encapsulation is permeable to gases, some corrosive substances such as H<sub>2</sub>S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



### Package Schematics



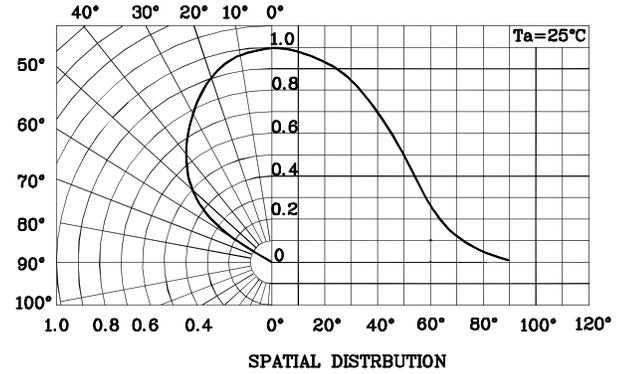
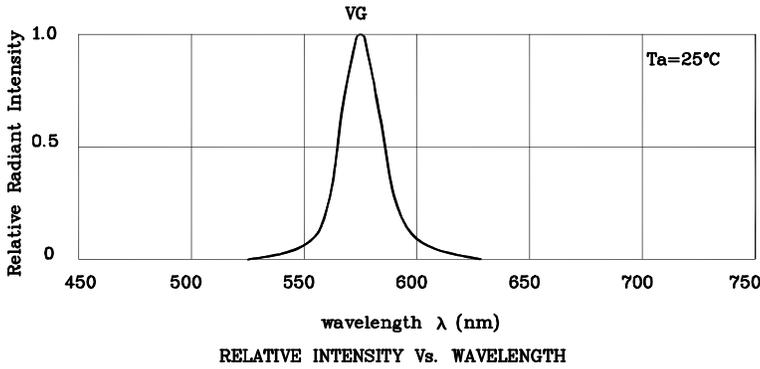
#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

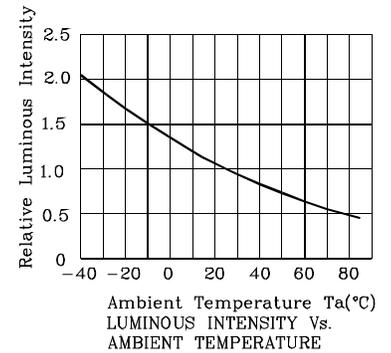
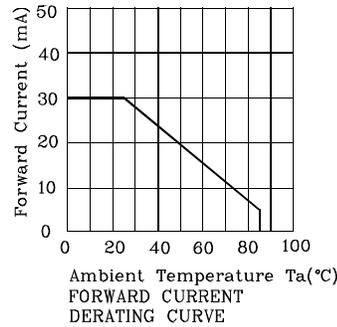
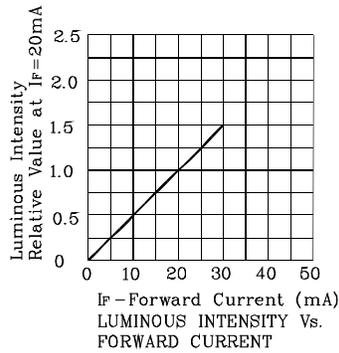
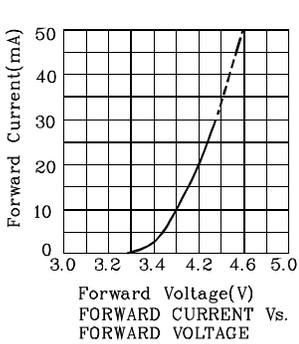
Absolute Maximum Ratings (T <sub>A</sub> =25°C)		VG (AlGaInP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	150	mA
Power Dissipation	P <sub>D</sub>	150	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (T <sub>A</sub> =25°C)		VG (AlGaInP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	4.2	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	5.0	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λ <sub>P</sub>	574	nm
Wavelength of Dominant Emission (Typ.) (I <sub>F</sub> =20mA)	λ <sub>D</sub>	570	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	Δλ	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	15	pF

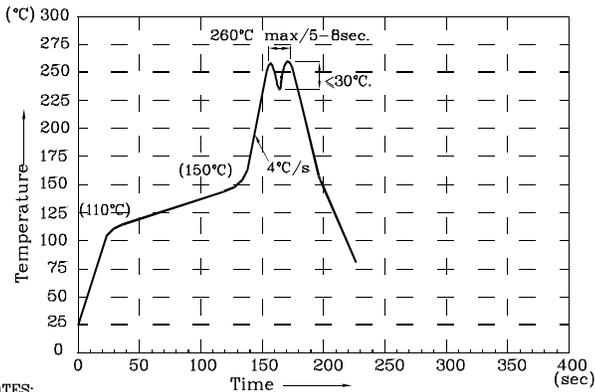
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =20mA)		Wavelength nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XZVG47S	Green	AlGaInP	Water Clear	55	118	574	100°



❖ VG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

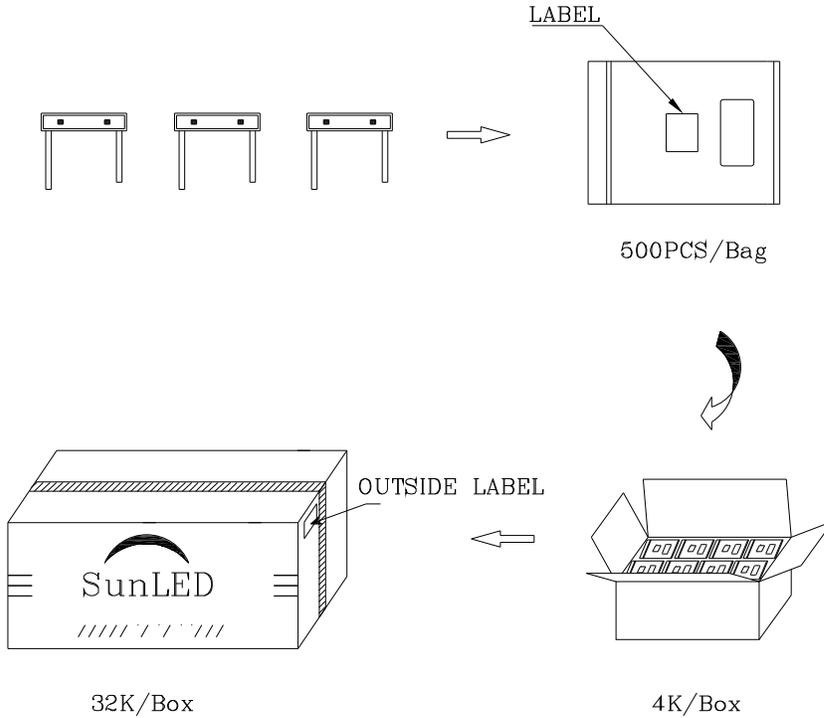
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

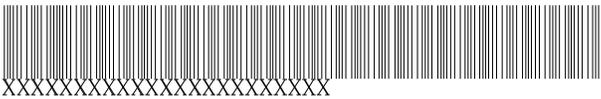
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**




Q.C. Q C  
XX XX. XXXX  
PASSED

P/NO : XZxxx47x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	